

PATENT
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/577,173

Filed: October 27, 2009

Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING
COMPOUND, SEMICONDUCTOR CHIP ND LEADFRAME AND METHOD FOR
PRODUCING THE SAME

Docket No.: I441.141.101

CHANGE OF ENTITY STATUS PURSUANT TO 37 C.F.R. § 1.27 (g)(1)

MAIL STOP M CORRESPONDENCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This communication hereby notifies the United States Patent and Trademark
Office that the Applicant hereby asserts small entity status for the above-identified patent
application.

Respectfully submitted,

DICKE BILLIG & CZAJA, PLLC

Date June 21, 2011

By /Mark L. Gleason/

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